Schottky Diodes Reverse Voltage-40to200v Forward current-3A

Features

Schottky chip

Ldeal for surface mounted applications

Low forward voltage drop, Low power loss, high efficiency

Plastic Case Material has UL Flammability

Mechanical Data

Package: SMAF

Terminals:Tin Plated leads, solderable per

Mil-STD-750 Method 2026

Polarity: As marked

Molding compound meets UL 94 V-0 flammability rating,

ROHS-compliant





Maximum Ratings (Ta=25℃ Unless otherwise specified)

meranian ratings (ra 10 0 0 most other most openiou)								
Type Number		SS34F	SS36F	SS38F	SS310F	SS315F	SS320F	Umit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	40	60	80	100	150	200	V
Maximum RMS Voltage	V_{RMS}	28	42	56	70	105	140	V
Maximum DC Blocking Voltage	V_{DC}	40	60	80	100	150	200	V
Maximum Average Forward Rectified Current	IO _(AV)	3.0						Α
Peak Forward Surge Current 8.3ms Single half-sine-wave superimposed on rated load(JEDEC Method) on rated IFSM			60	60.0			Α	
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25℃		120.0				Α		
Current squared time @1ms≤t8.3≤ms Tj=25℃,Rating of per diode	l ² t	14.9					A ² S	
Maximum Forward Voltage at 3.0A DC	V_{FM}	0.55	0.75	0.	85	0.9	92	V
Maximum Reverse Current TA = 25℃	ID	0.1 0.05			mA			
at Rated DC Blocking Voltage TA = 100℃	IIX	20 10					mA	
Typical Thermal Resistance	R_{QJA}	65.0			.C\M			
Operating Junction Temperature Range	T_J	—55to+150			$^{\circ}\!\mathbb{C}$			
Storage Temperature Range	T _{STG}	—55to+150			${\mathbb C}$			
Maximum Reverse Current TA = 25℃ at Rated DC Blocking Voltage TA = 100℃ Typical Thermal Resistance Operating Junction Temperature Range	- IR R _{QJA} T _J	0.		10 65.0 —55to+150			r °(

FIG. 1MAXIMUM AVERAGE FORWARD CURRENT DERATING

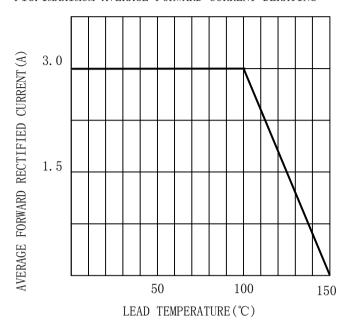


FIG. 2TYPICAL FORWARD CHARACTERISTICS

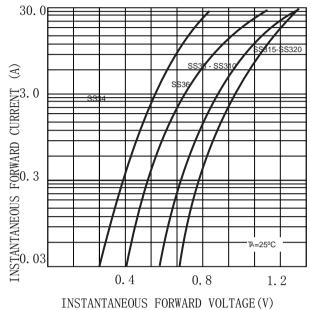


FIG. 3MAXIMUM NON-REPEITIVE SURGE CURRENT

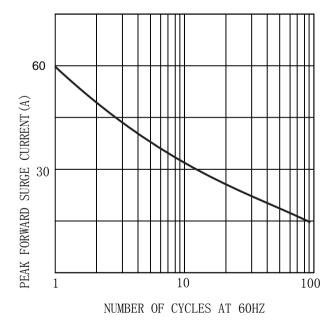
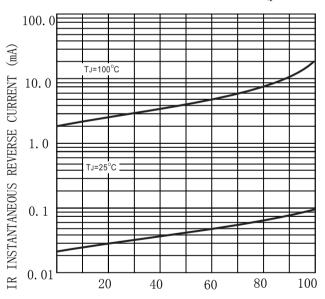


FIG. 4 TYPICAL REVERSE CHARACTERISTICS (per element)



PERCENT OF RATED PEAK REVERSE VOLTAGE (%)

MARKING INFORMATION



🤝 = Logo

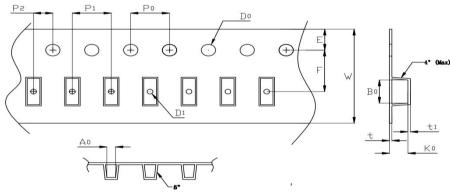
**** = Date Code Marking

SS**= Marking Code

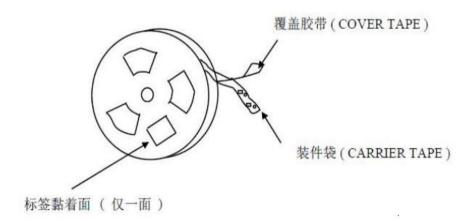
Print according to customer request

PACKING REQUIRMENTS

Carrier tape packing



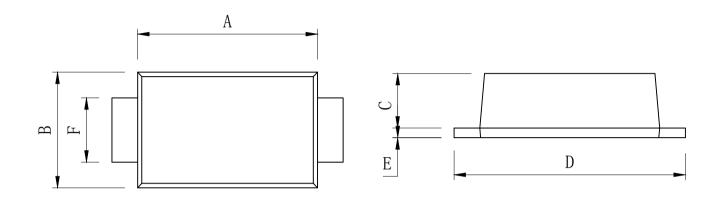
Specificati ons	Carrier tape type	Ao	Во	Ко	Ро	W	t	Exiplain
SMAF	Anti-static	2.83± 0.10	4.9± 0.10	1.45± 0.05	4.00± 0.10	12.0± 0.10	0.23± 0.05	



DEVICE TYPE	Tape width		13"Reel		7"Reel			
		Q'TY/REEL (pcs)	BOX/CAR TOON	Q'TY/REEL (pcs)	Q'TY/REEL (pcs)	BOX/CAR TOON	Q'TY/REEL (pcs)	
SMAF	12mm	10000	20	200000	3000	64	192000	

Outline Dimensions

SMAF



SMAF							
DIM	INC	HES	MM				
	MIN	MAX	MIN	MAX			
A	0. 13	0. 15	3.2	3.8			
В	0.09	0. 11	2.3	2. 7			
С	0.03	0.05	0.8	1.2			
D	0. 16	0.20	4	5			
Е	/	0.01	/	0.3			
F	0.04	0.08	1	2			

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